

Absolute Maximum Ratings at $T_j=25$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	80	V
Gate source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_C=25$ °C	I_D	250	A
Pulsed drain current ²⁾ , $T_C=25$ °C	$I_{D, pulse}$	750	A
Continuous diode forward current ¹⁾ , $T_C=25$ °C	I_S	250	A
Diode pulsed current ²⁾ , $T_C=25$ °C	$I_{S, pulse}$	750	A
Power dissipation ³⁾ , $T_C=25$ °C	P_D	300	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	1000	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R	0.42	°C/W
Thermal resistance, junction-ambient ⁴⁾	R	62	°C/W

Electrical Characteristics at $T_j=25$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	80			V	$V_{GS}=0$ V, $I_D=250$ A
Gate threshold voltage	$V_{GS(th)}$	2.0		4.0	V	$V_{DS}=V_{GS}$, $I_D=250$ A
Drain-source on-state resistance	$R_{DS(ON)}$		2.9	3.2		$V_{GS}=10$ V, $I_D=30$ A
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=20$ V
				-100		$V_{GS}=-20$ V
Drain-source leakage current	I_{DSS}			1	A	$V_{DS}=80$ V, $V_{GS}=0$ V

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		9322		pF	$V_{GS}=0\text{ V}$, $V_{DS}=40\text{ V}$, 00 kHz
Output capacitance	C_{oss}		2710		pF	
Reverse transfer capacitance	C_{rss}		91		pF	
Turn-on delay time	$t_{d(on)}$		36.1		ns	$V_{GS}=10\text{ V}$, $V_{DS}=50\text{ V}$, R_G $I_D=25\text{ A}$
Rise time	t_r		42.3		ns	
Turn-off delay time	$t_{d(off)}$		102.3		ns	
Fall time	t_f		30.5		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		148.4		nC	$V_{GS}=10\text{ V}$, $V_{DS}=50\text{ V}$, $I_D=25\text{ A}$
Gate-source charge	Q_{gs}		34.5		nC	
Gate-drain charge	Q_{gd}		40.9		nC	
Gate plateau voltage	$V_{plateau}$		4.7		V	

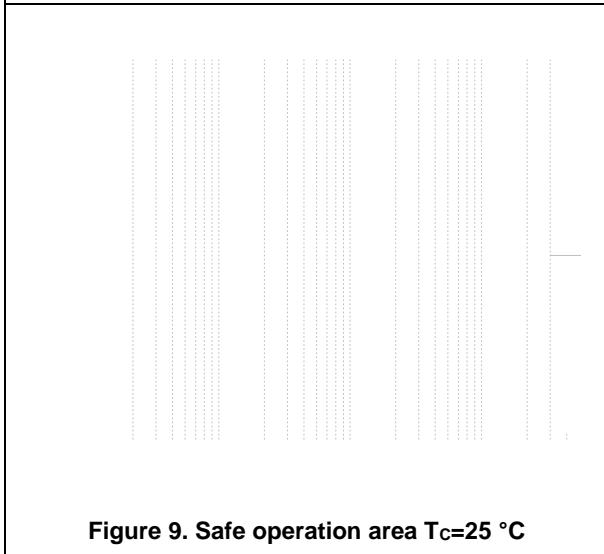
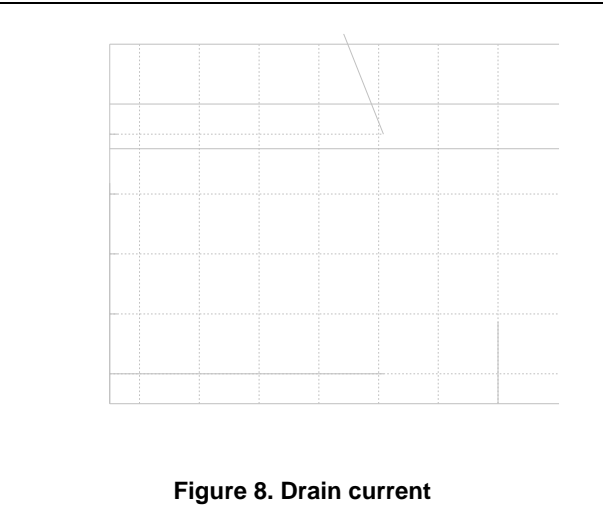
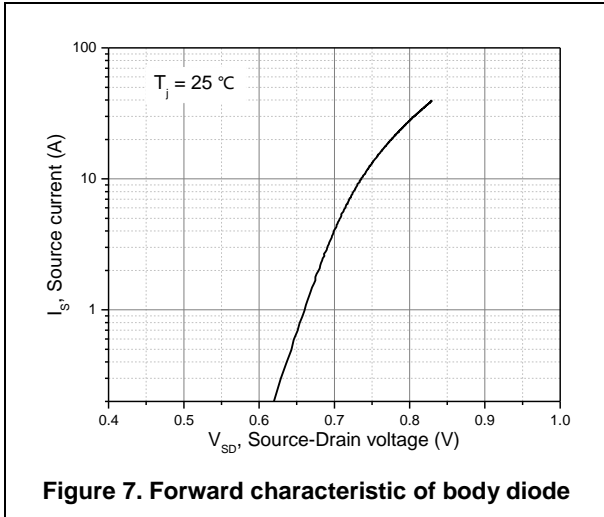
Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V_{SD}			1.3	V	$I_S=25\text{ A}$, $V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		108.2		ns	$V_R=50\text{ V}$, $I_S=25\text{ A}$,
Reverse recovery charge	Q_{rr}		428.9		nC	
Peak reverse recovery current	I_{rrm}		6.5		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta j-c}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ °C}$.
- 5) $V_{DD}=50\text{ V}$, $V_{GS}=10\text{ V}$, $L=0.3\text{ mH}$, starting $T_j=25\text{ °C}$.

Enhancement Mode N-



Test circuits and waveforms

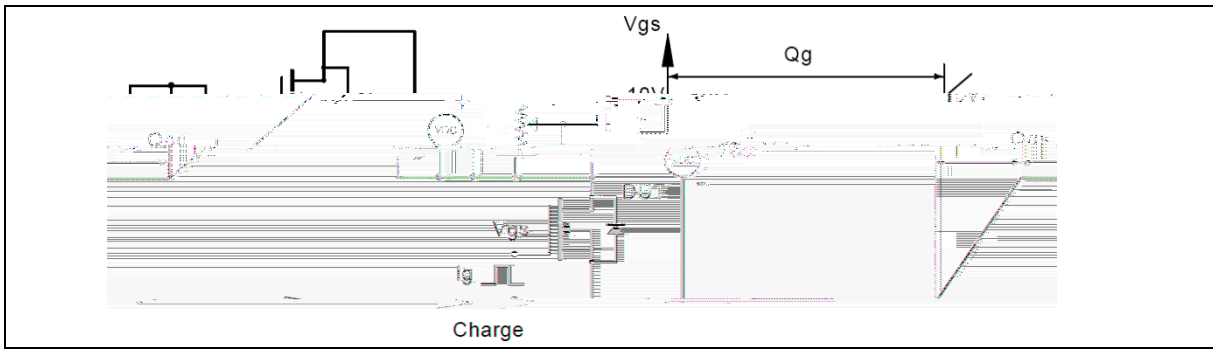


Figure 1. Gate charge test circuit & waveform

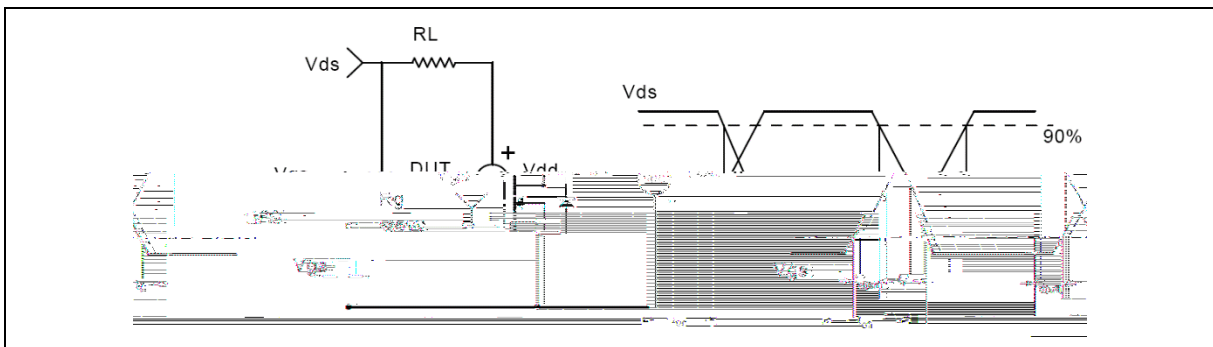


Figure 2. Switching time test circuit & waveforms

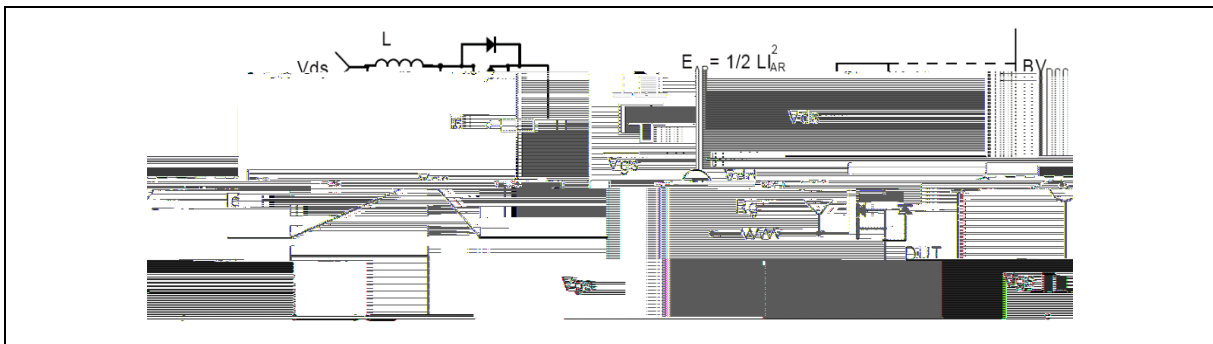


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

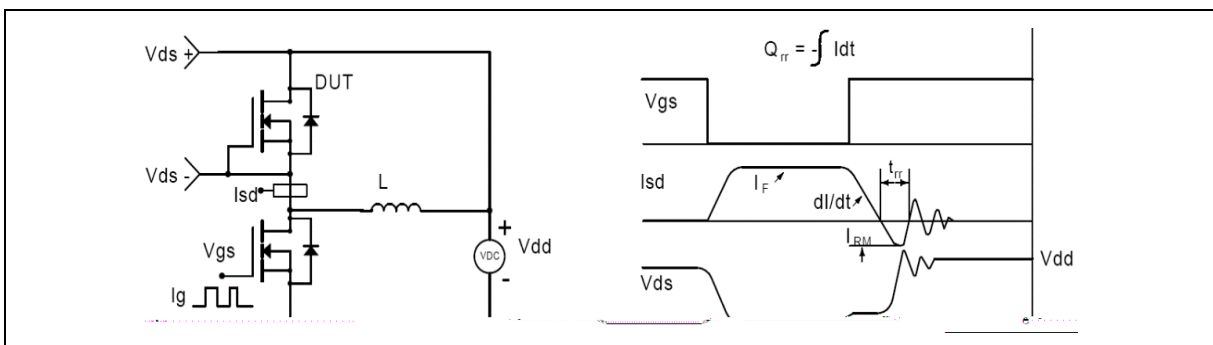
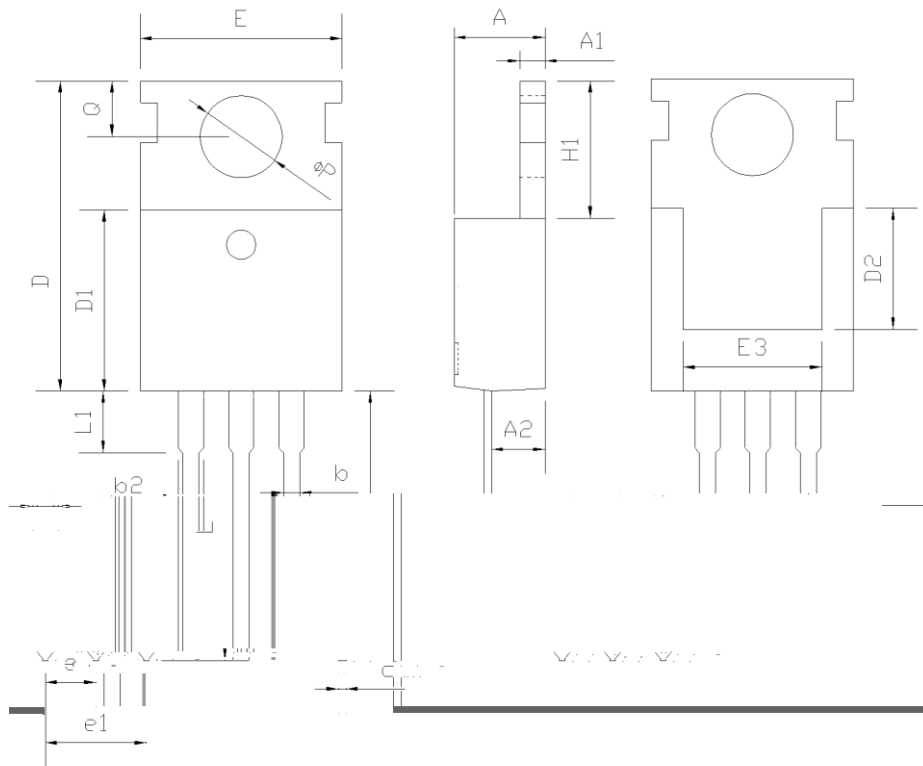


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	4.37	4.57	4.77
A1	1.25	1.30	1.45
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b2	1.17	1.27	1.47
c	0.40	0.50	0.65
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50	-	-
E	9.70	10.00	10.30
E3	7.00	-	-
e	2.54 BSC		
e1	5.08 BSC		
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1	-	3.10	3.40
	3.40	3.60	3.80
Q	2.60	2.80	3.00

Version 1: TO220-C package outline dimension

Ordering Information

Package Type	Units/ Tube	Tubes / Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
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